

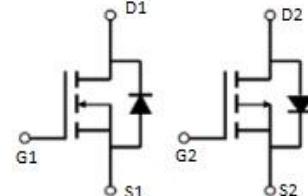
Features

- N+P Channel
- Very Low on-resistance



Applications

- Motor Control.
- Synchronous Rectification.



Absolute Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Value		Unit
		NMOS	PMOS	
Drain-Source Voltage	V_{DSS}	80	-80	V
Drain Current-continuous	I_D	$T_c=25^\circ\text{C}$	3.4	A
		$T_c=100^\circ\text{C}$	1.7	A
Drain Current-pulse (note 1)	I_{DM}	13.6	-10.4	A
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Avalanche Current, single pulse($L=0.5\text{mH}$)	I_{AS}	5.4	-4.2	A
Avalanche Energy, single pulse($L=0.5\text{mH}$)	E_{AS}	7.29	4.41	mJ
Power Dissipation (SOP-8)	P_D	$T_c=25^\circ\text{C}$	2.0	W
		$T_c=100^\circ\text{C}$	1.4	W
Power Dissipation (DFN5x6)	P_D	$T_c=25^\circ\text{C}$	2.8	W
		$T_c=100^\circ\text{C}$	1.1	W
Maximum Junction Temperature	T_J	150		$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ 150		$^\circ\text{C}$

*Drain current limited by maximum junction temperature

N-Channel Electrical Characteristics

Parameter	Symbol	Tests conditions	Min	Type	Max	Units
Drain-Source Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	80	-	-	V

Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=80V, V_{GS}=0V, T_c=25^\circ C$	-	-	1	μA
		$V_{DS}=80V, T_c=85^\circ C$	-	-	30	μA
Gate body leakage current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 10	μA
On-Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	2	3	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.4A, T_c=25^\circ C$	-	130	-	$m\Omega$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=1.7A, T_c=25^\circ C$	-	134	-	$m\Omega$
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS}=20V, V_{GS}=0V, f=1.0MHz$	-	1300	-	pF
Output capacitance	C_{oss}		-	200	-	pF
Reverse transfer capacitance	C_{rss}		-	40	-	pF
Gate Resistance	R_G	$V_{DS}=0V, V_{GS}=0V, f=1.0MHz$	-	2.5	-	Ω
Forward Transfer Admittance	g_{fs}	$V_{DS} = 10V, I_D = 3.4A$	3.0	-	-	S

Electrical Characteristics($T_{CASE}=25^\circ C$ unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Type	Max	Units
Switching-Characteristics						
Turn-On delay time	$t_{d(on)}$	$V_{DD}=20V, I_D=1.7A, R_L=20\Omega, R_G=6\Omega, V_{GEN}=10V$	-	7.8	-	ns
Turn-On rise time	t_r		-	6.9	-	ns
Turn-Off delay time	$t_{d(off)}$		-	22.4	-	ns
Turn-Off rise time	t_f		-	4.8	-	ns
Total Gate Charge	Q_g	$V_{DS}=40V, I_D=3.4A, V_{GS}=5V$	-	6.6	-	nC
Gate-Source charge	Q_{gs}		-	1.8	-	nC
Gate-Drain charge	Q_{gd}		-	2.2	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=1.7A$	-	0.78	1.1	V

Reverse Recovery Time	T _{rr}	I _{ds} =1.7A, disd/dt=100A/us		13		ns
Reverse Recovery Charge	Q _{rr}			8.7		nC

P-Channel Electrical Characteristics

Parameter	Symbol	Tests conditions	Min	Type	Max	Units
Drain-Source Voltage	BV _{DSS}	I _D =-250μA, V _{GS} =0V	-80	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-80V, V _{GS} =0V, T _C =25°C	-	-	-1	μA
		V _{DS} =-80V, T _C =85°C	-	-	-30	μA
Gate body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA

On-Characteristics

Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.5	-2	-3	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-2.6A, T _C =25°C	-	258	-	mΩ
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-1.3A, T _C =25°C	-	290	-	mΩ

Dynamic Characteristics

Input capacitance	C _{iss}	V _{DS} =-25V, V _{GS} =0V, f=1.0MHz	-	1419	-	pF
Output capacitance	C _{oss}		-	230	-	pF
Reverse transfer capacitance	C _{rss}		-	45	-	pF
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	8	-	Ω
Forward Transfer Admittance	g _{fs}	V _{DS} =-10V, I _D =-2.6A	2.0			S

Electrical Characteristics (T_{CASE}=25°C unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Type	Max	Units
Switching-Characteristics						
Turn-On delay time	t _{d(on)}	V _{DD} =-40V, I _{DS} =-1.3A, R _G =6Ω, V _{GEN} =-10V, R _L =20Ω	-	8.7	-	ns
Turn-On rise time	t _r		-	7	-	ns
Turn-Off delay time	t _{d(off)}		-	31	-	ns
Turn-Off rise time	t _f		-	17	-	ns

Total Gate Charge	Q_g	$V_{DS}=-40V, I_D=-2.6A, V_{GS}=-5.0V$	-	8.2	-	nC
Gate-Source charge	Q_{gs}		-	2.5	-	nC
Gate-Drain charge	Q_{gd}		-	2.5	-	nC

Drain-Source Diode Characteristics and Maximum Ratings

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-1.3A$	-	-	-1.2	V
Reverse Recovery time	T_{rr}	$I_S=-2.6A, \frac{dI_{sd}}{dt}=100A/\mu s$	-	15	-	ns
Reverse Recovery Charge	Q_{rr}		-	8	-	nC

Thermal Characteristic

Parameter	Symbol	Value		Unit
		SOP8	DFN5x6	
Thermal Resistance, Junction to Ambient	$R_{th}(J-A)^2$	62.5	45	°C/W
	$R_{th}(J-A)^3$	89.2	68.5	°C/W

Notes:

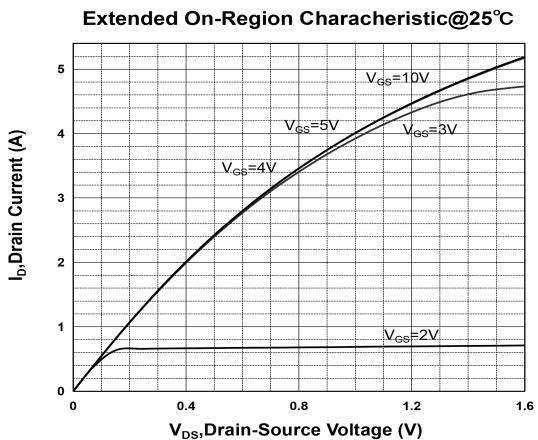
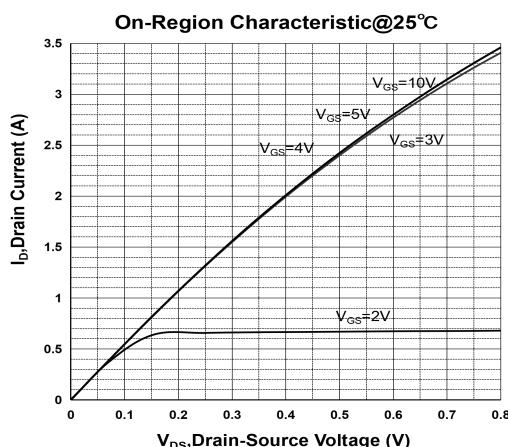
1. Pulse width limited by maximum junction temperature
2. Mounted on a ceramic board (30×30×0.8mm)
3. Mounted on a Cu board (40×40×0.8mm)

Order Message

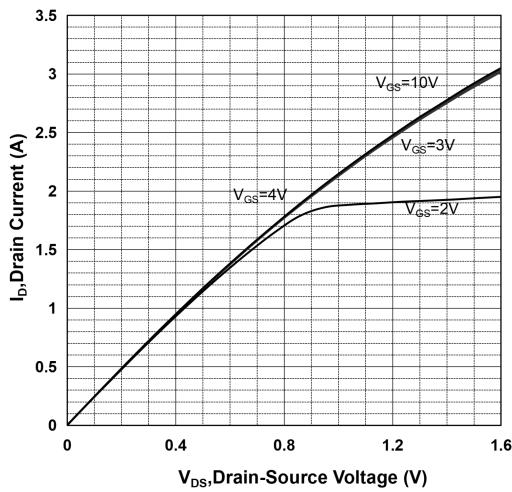
Marking	Package
MSPN0308S0	SOP8
MSPN0308N2	DFN 5x6

ELECTRICAL CHARACTERISTICS (curves)

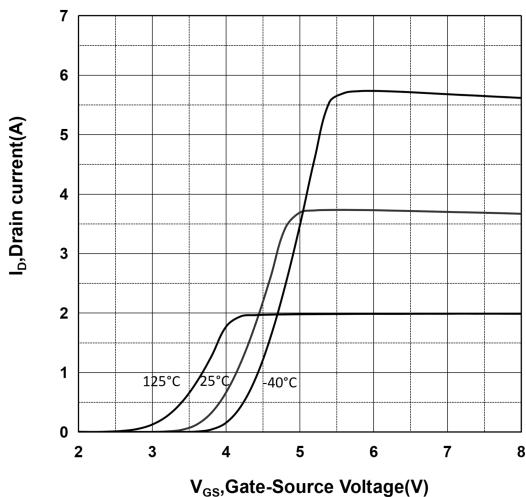
N-Channel



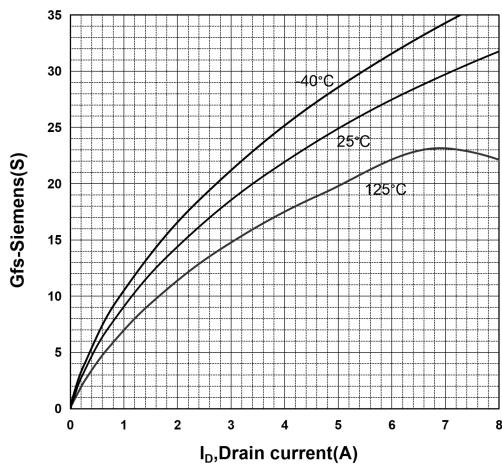
On-Region Characteristic@125°C



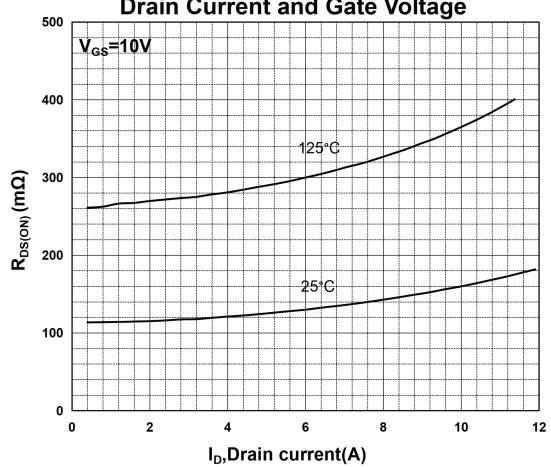
Transfer Characteristics



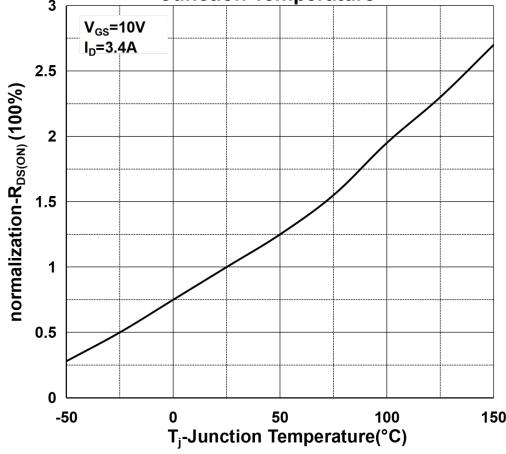
Transconductance



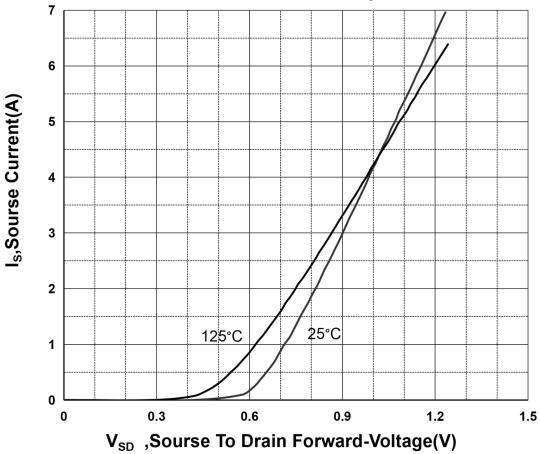
On-Resistance Variation vs Drain Current and Gate Voltage

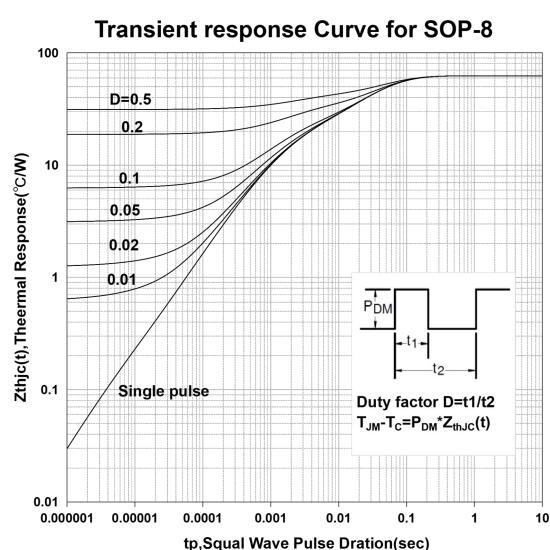
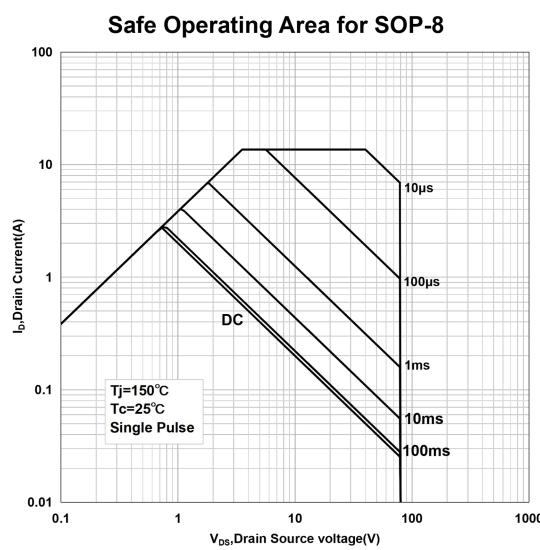
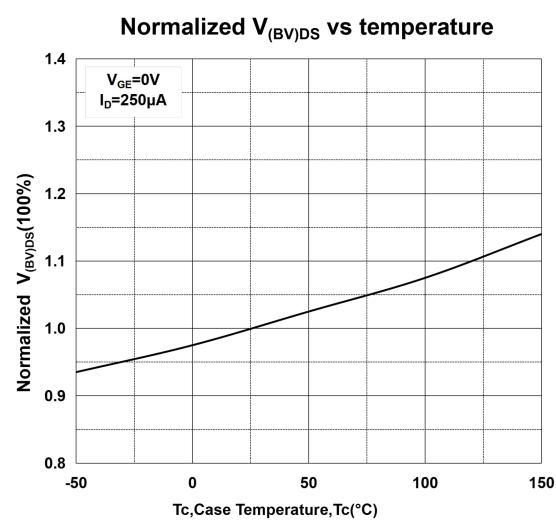
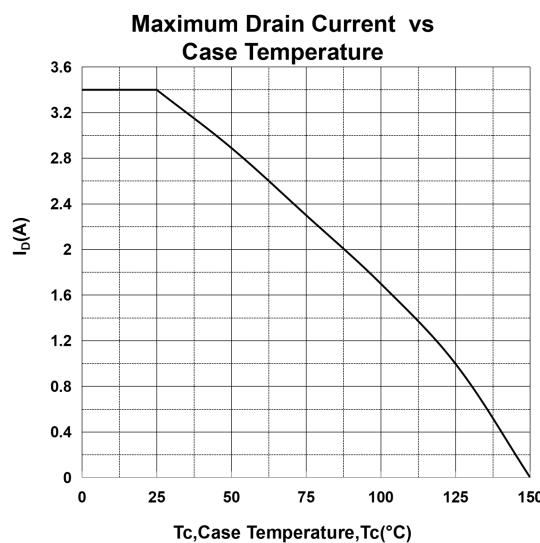
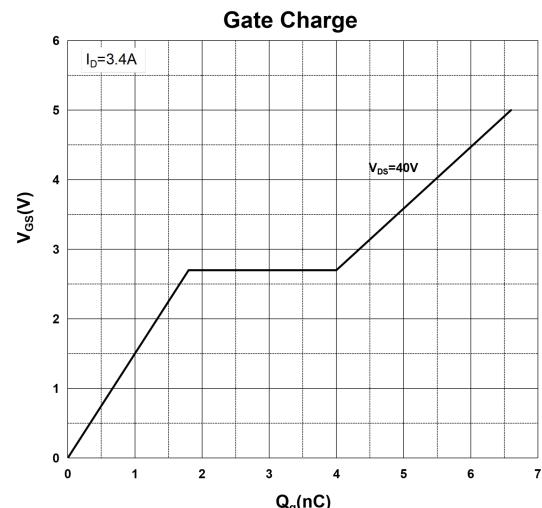
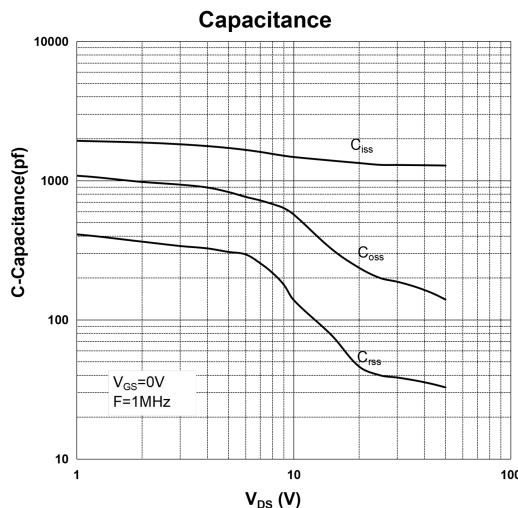


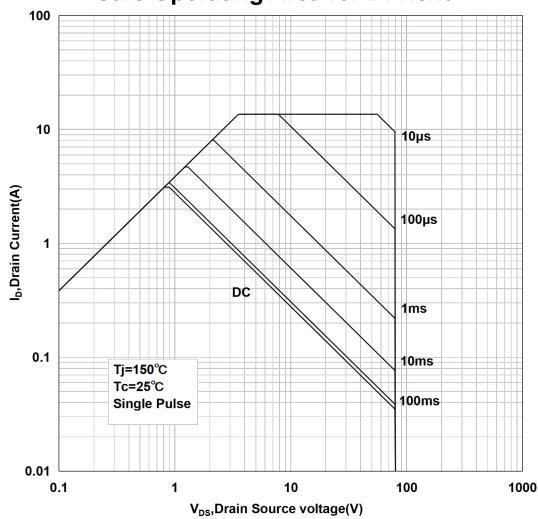
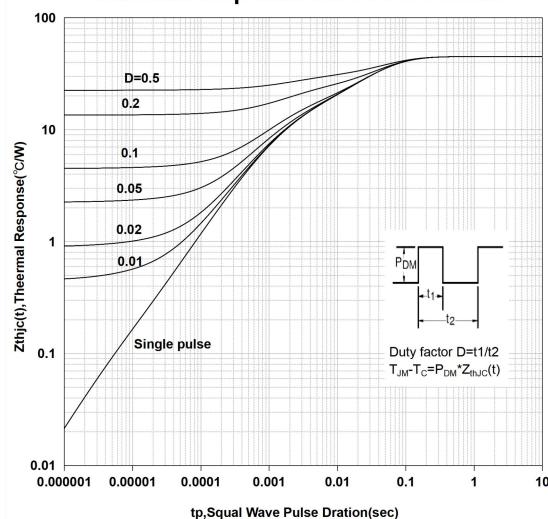
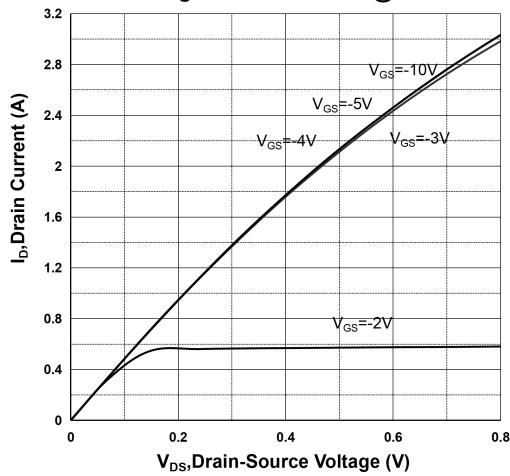
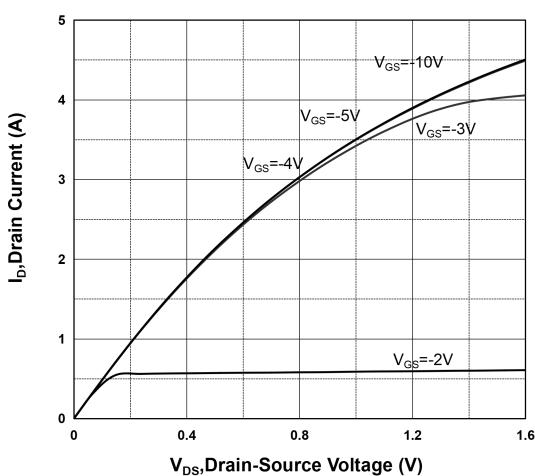
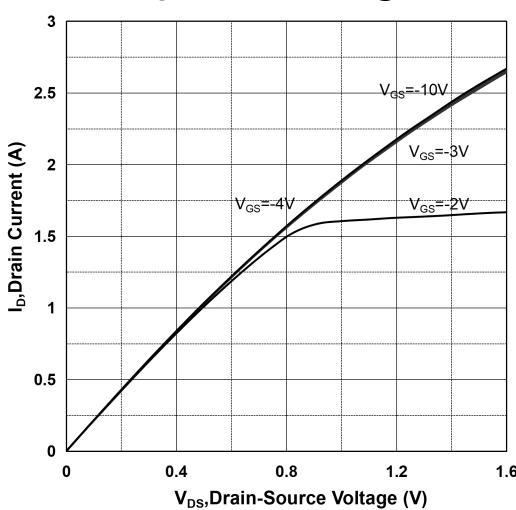
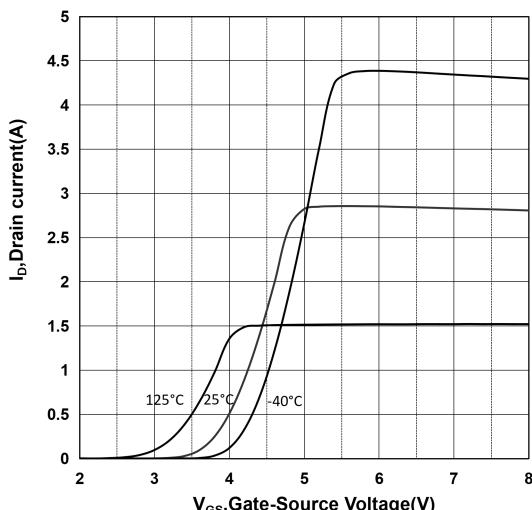
Normalization On-Resistance Variation vs Junction Temperature



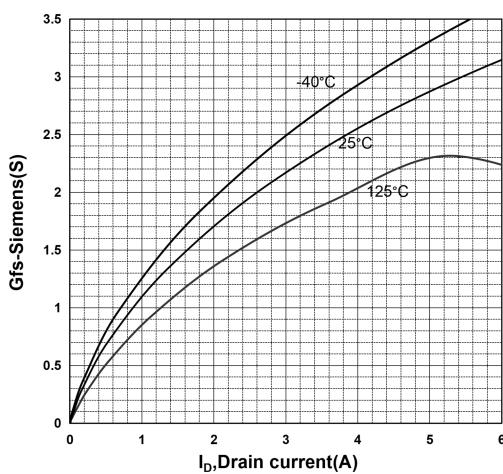
Body Diode Forward Voltage Variation with Source Current and Temperature



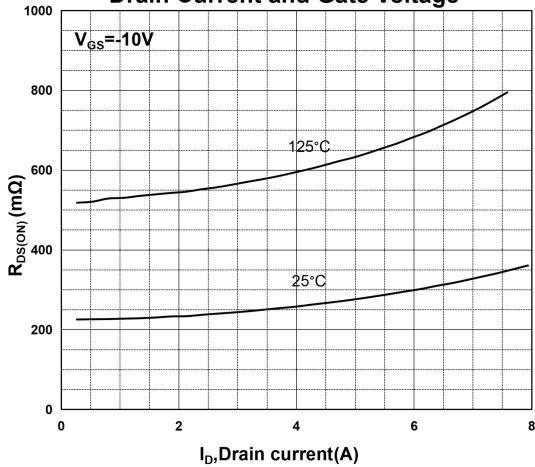


Safe Operating Area for DFN5x6

Transient response Curve for DFN5x6

P-Channel
On-Region Characteristic@25°C

Extended On-Region Characheristic@25°C

On-Region Characteristic@125°C

Transfer Characteristics


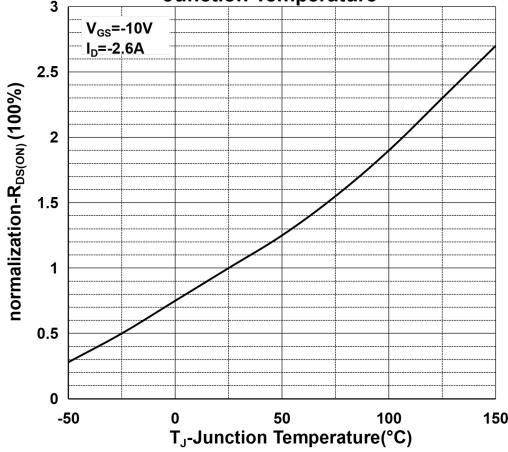
Transconductance



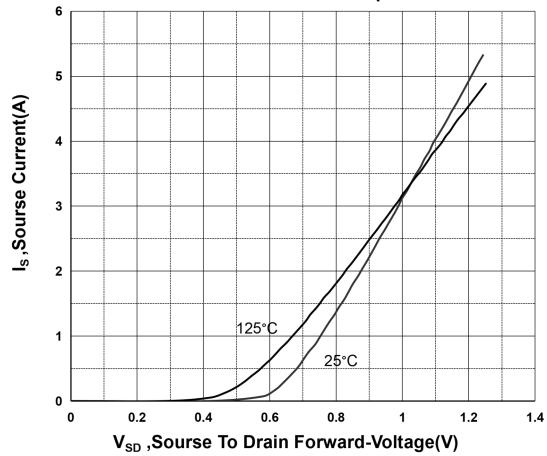
On-Resistance Variation vs Drain Current and Gate Voltage



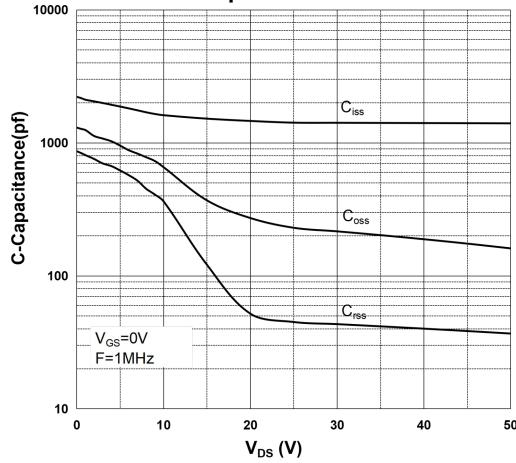
Normalization On-Resistance Variation vs Junction Temperature



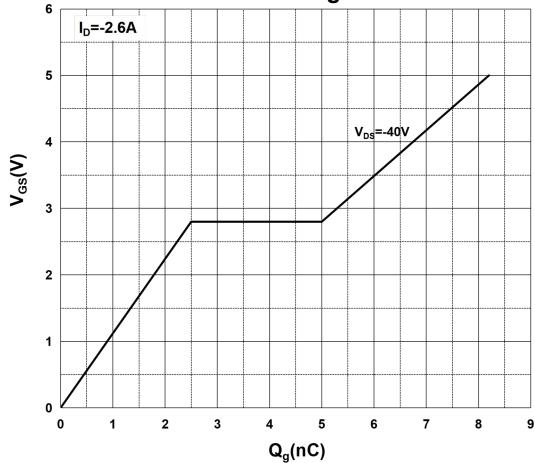
Body Diode Forward Voltage Variation with Source Current and Temperature

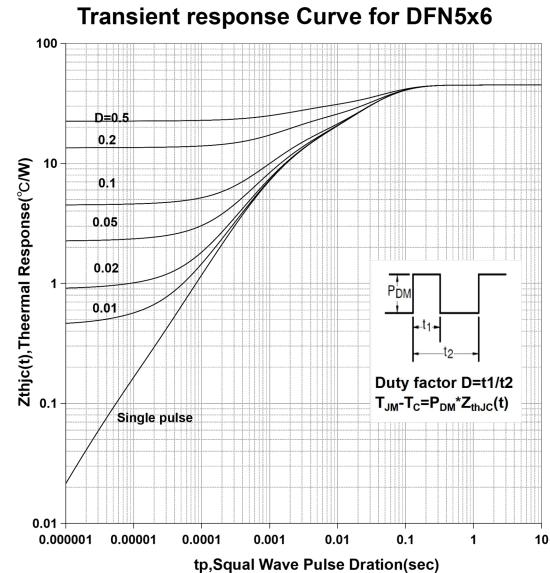
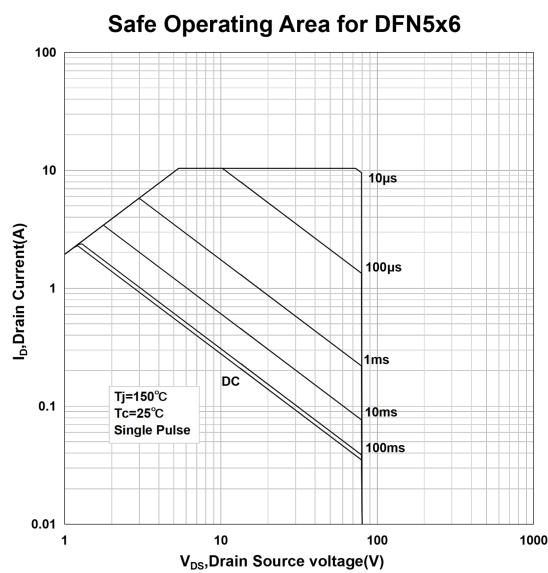
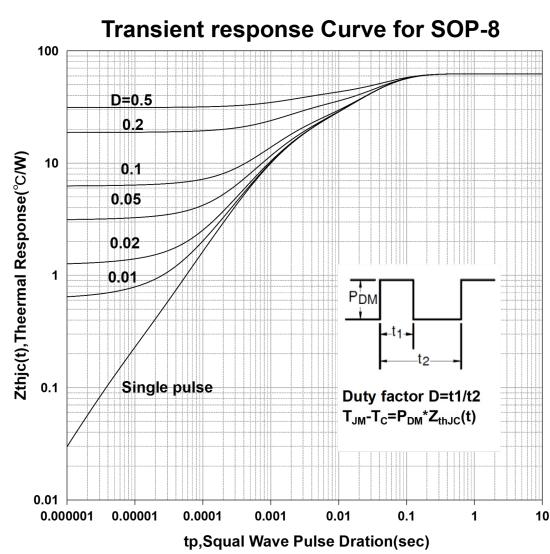
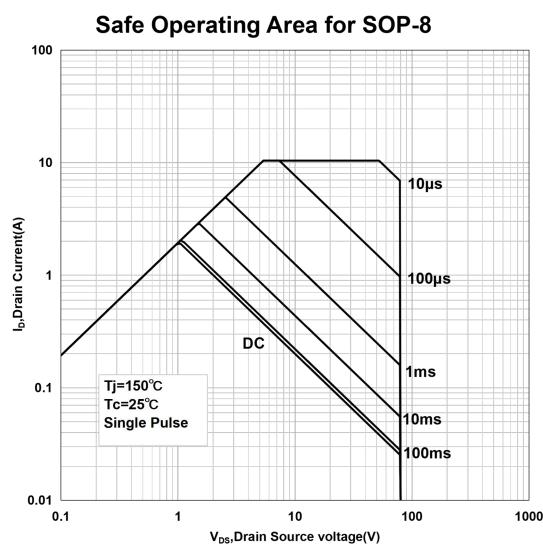
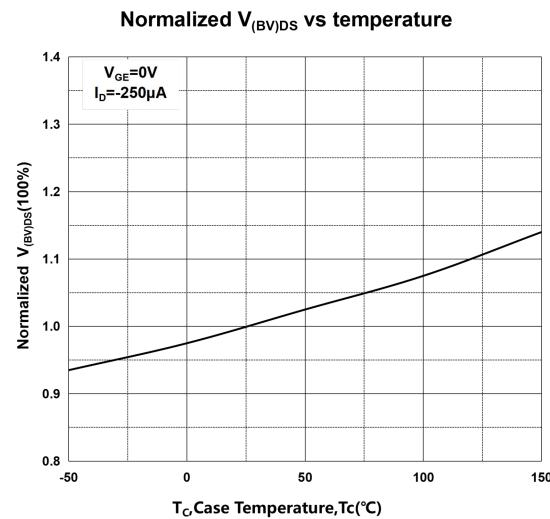
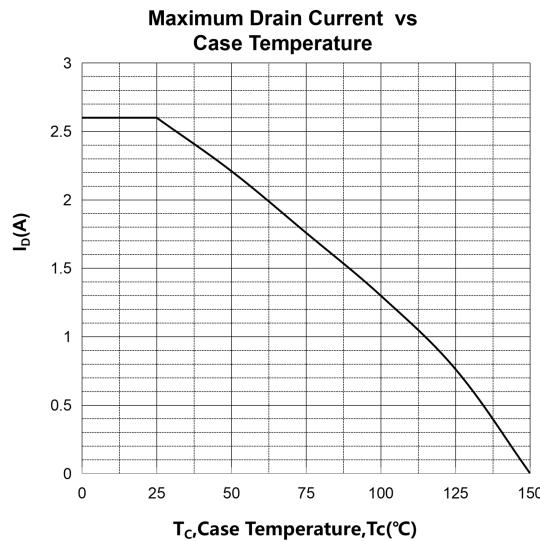


Capacitance



Gate Charge





N-Channel Measurement circuit

Fig.1-1 Switching Time Measurement Circuit

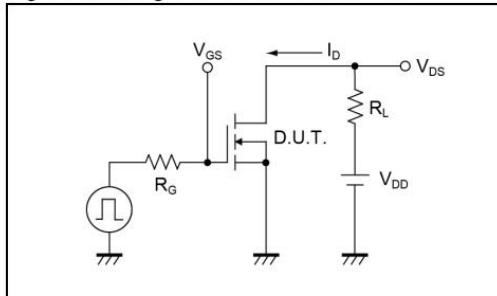


Fig.1-2 Switching Waveforms

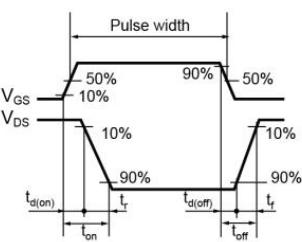


Fig.2-1 Gate Charge Measurement Circuit

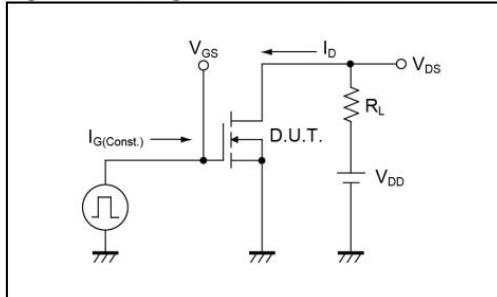
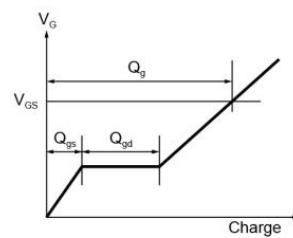


Fig.2-2 Gate Charge Waveform



P-Channel Measurement circuit

Fig.3-1 Switching Time Measurement Circuit

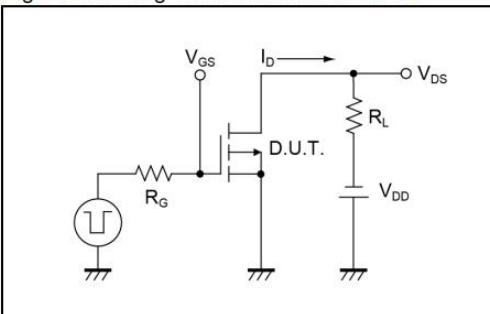


Fig.3-2 Switching Waveforms

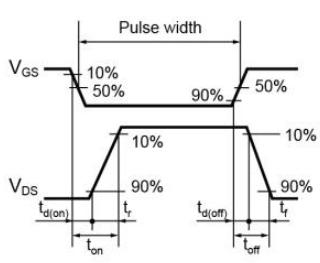


Fig.4-1 Gate Charge Measurement Circuit

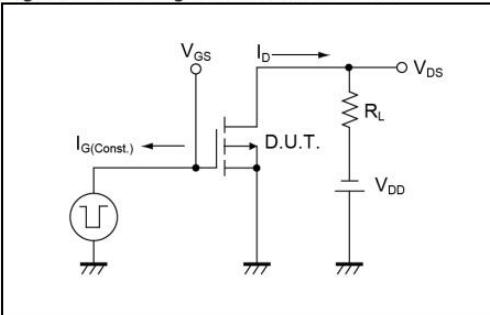
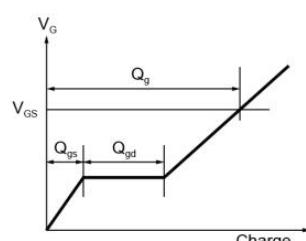
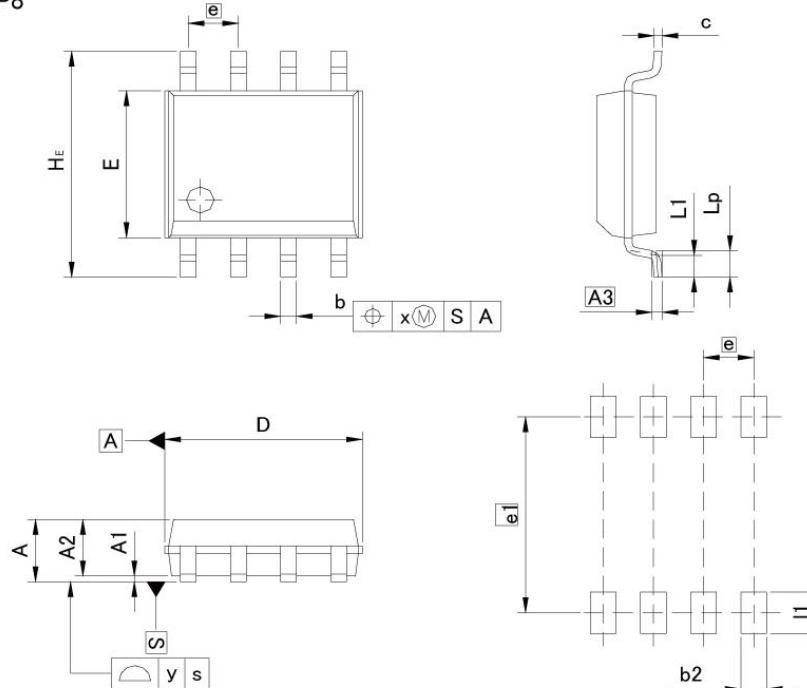


Fig.4-2 Gate Charge Waveform



PACKAGE MECHANICAL DATA

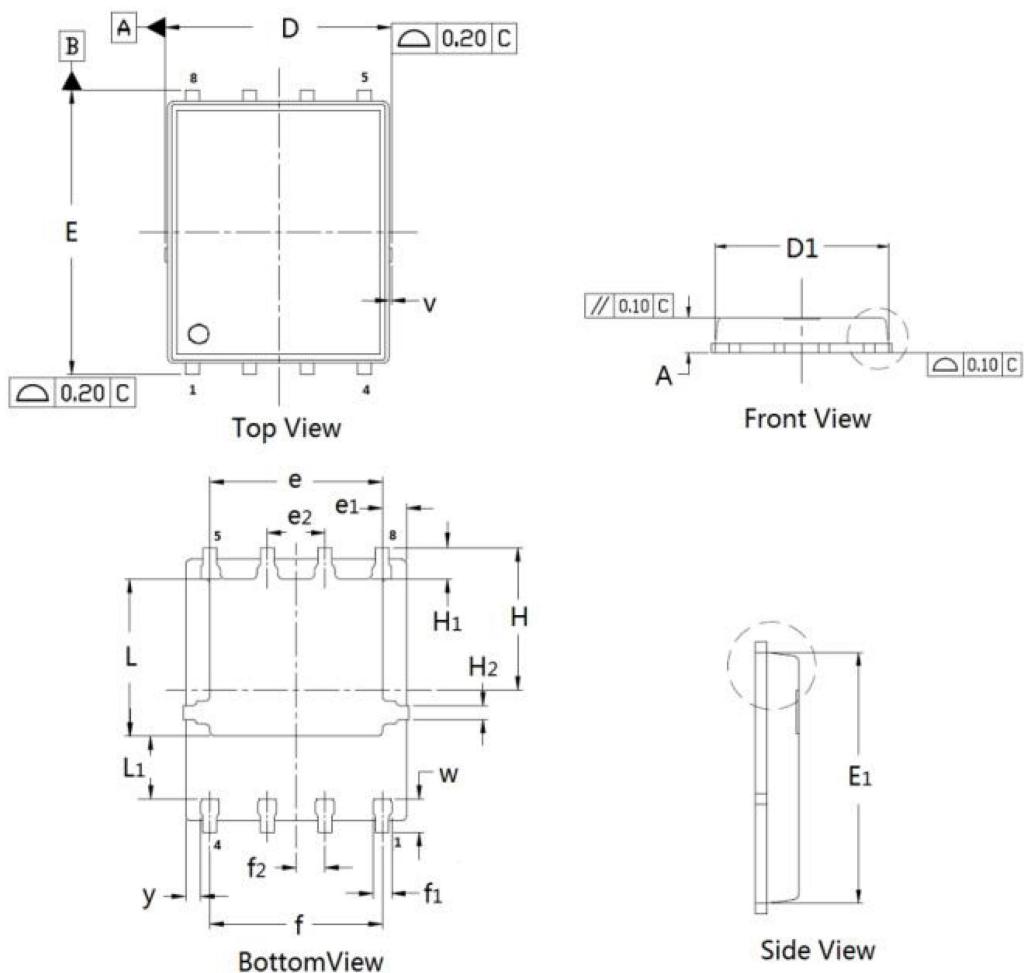
SOP8

Pattern of terminal position areas
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	1.75	—	0.069
A ₁	0.15		0.006	
A ₂	1.40	1.60	0.055	0.063
A ₃	0.25		0.010	
b	0.30	0.50	0.012	0.020
c	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
e	1.27		0.050	
H _E	5.70	6.30	0.224	0.248
L ₁	0.40	0.60	0.016	0.024
L _p	0.65	0.85	0.026	0.033
x	0.15		0.006	
y	0.10		0.004	

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b ₂	—	0.65	—	0.026
e ₁	5.15		0.203	
I ₁	—	1.15	—	0.045

Dimension in mm/inches



DFN 5x6

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D ₁	4.80	4.89	5.00	E	6.00	6.11	6.20
E ₁	5.65	5.74	5.85	e	3.72	3.80	3.92
e ₁	--	0.54	--	e ₂	--	1.27	--
f	--	3.82	--	f ₁	0.31	0.37	0.51
f ₂	--	0.64	--	H	--	3.15	--
H ₁	0.59	0.63	0.79	H ₂	0.26	0.28	0.32
L	3.38	3.45	3.58	L ₁	--	1.39	--
v	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--